

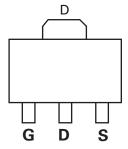
N-Channel 60-V (D-S) MOSFET

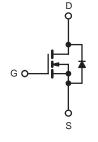
PRODUCT SUMMARY							
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)					
60	0.030 at V _{GS} = 10 V	8.0					
	0.034 at V _{GS} = 4.5 V	6.5					

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage	V _{DS}	6	V		
Gate-Source Voltage	V _{GS}	±			
Continuous Drain Current (T _J = 175 °C) ^a	T _A = 25 °C	la la	8.0	7.0	А
Continuous Drain Current $(1_j = 175 \text{ C})$	T _A = 70 °C	۱ _D	6.4	5.6	
Pulsed Drain Current	I _{DM}	4	A		
Avalanche Current	I _{AS}	1			
Single Pulse Avalanche Energy	E _{AS}	1	mJ		
Maximum Davies Disain ation?	T _A = 25 °C	P _D	3.3	1.7	w
Maximum Power Dissipation ^a	T _A = 70 °C	' D	2.3	1.2	vv
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 t	°C		

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Mauinum hursting to Archingt a	t ≤ 10 s	R _{thJA}	36	45				
Maximum Junction-to-Ambient ^a	Steady State	``thJA	75	90	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	20				

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit			
Static				.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		3111			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	60			V			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1		3	V			
Gate-Body Leakage					± 100	nA			
Zaro Cata Voltago Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA			
Zero Gate Voltage Drain Current		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C			20				
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	40			А			
		V _{GS} = 10 V, I _D = 6.0 A		0.030					
Drain-Source On-State Resistance ^a	P	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.0 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$		0.035		Ω			
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 6.0 A, T _J = 175 °C		0.040					
		V _{GS} = 4.5 V, I _D = 5.1 A		0.034					
Forward Transconductancea	9 _{fs}	V _{DS} = 15 V, I _D = 6.0 A		25		S			
Diode Forward Voltage ^a	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V			
Dynamic ^b				•					
Total Gate Charge	Qg			18	27				
Gate-Source Charge	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 6.0 A		3.4		nC			
Gate-Drain Charge	Q _{gd}			5.3					
Gate Resistance	Rg	V _{GS} = 0.1 V, f = 5 MHz	0.5	1.4	2.4	Ω			
Turn-On Delay Time	t _{d(on)}			10	20				
Rise Time	t _r	V_{DD} = 30 V, R_L = 30 Ω		10	20	ns			
Turn-Off Delay Time	t _{d(off)}	$I_{D}\cong$ 1 A, V_{GEN} = 10 V, R_{g} = 6 Ω		25	50				
Fall Time	t _f			12	24				
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.7 A, dl/dt = 100 A/μs		50	80				

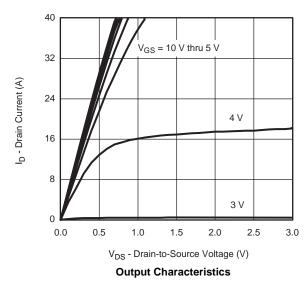
Notes:

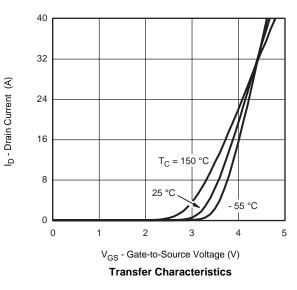
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

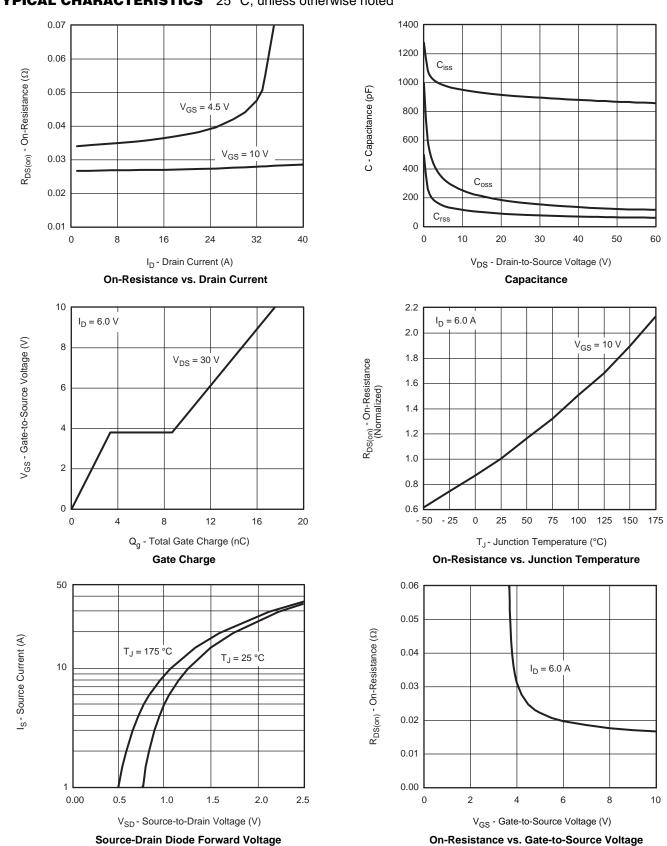
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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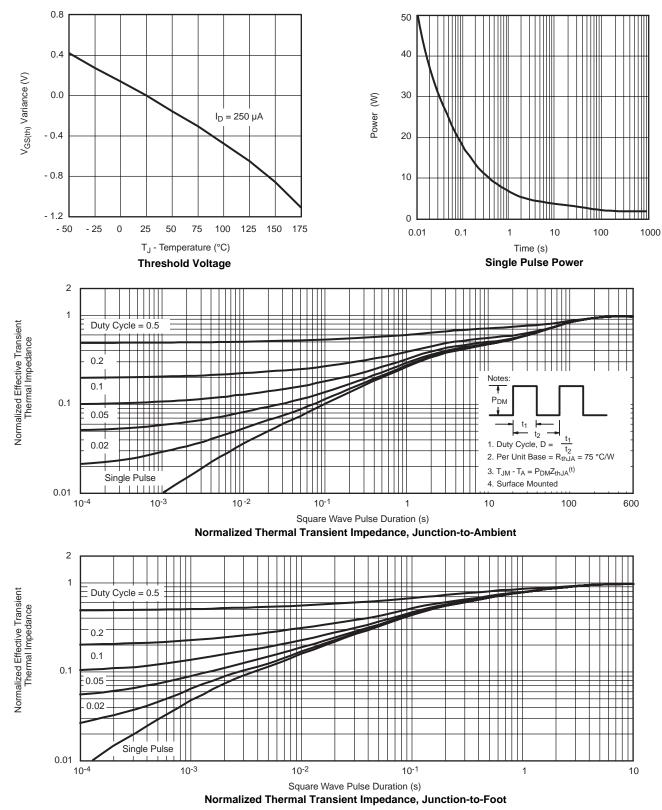




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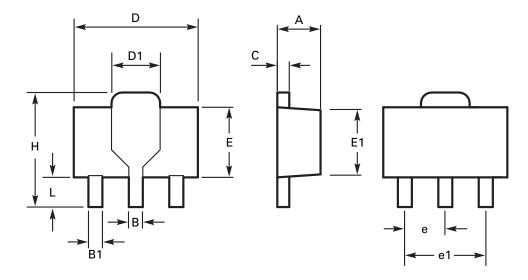








Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
А	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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